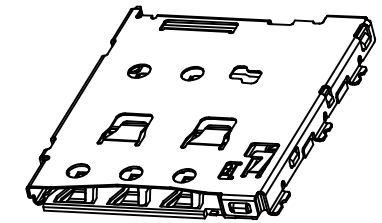
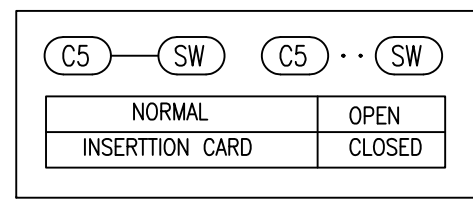
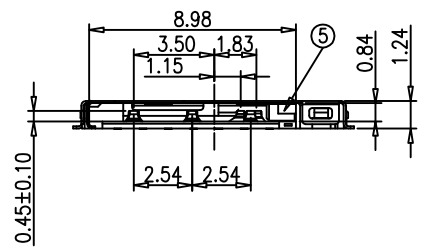
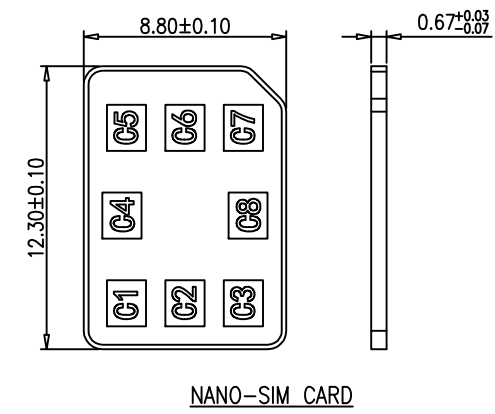
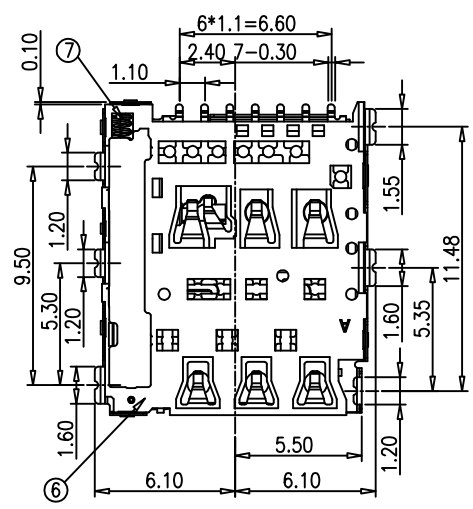
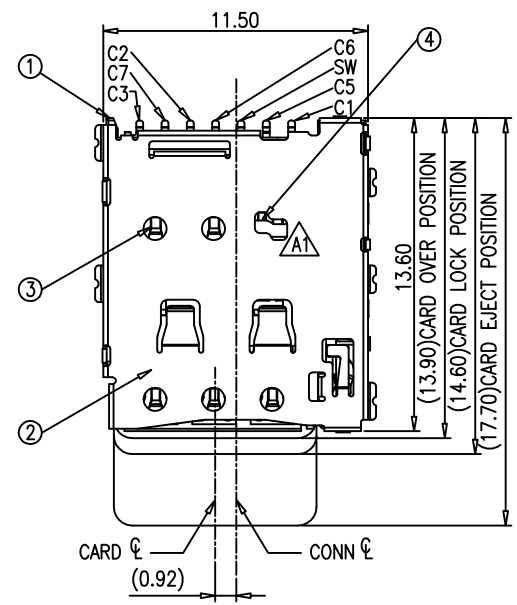


更改	REV	修改内容	MODIFICATION
A	EC05997		
B	EC06856		



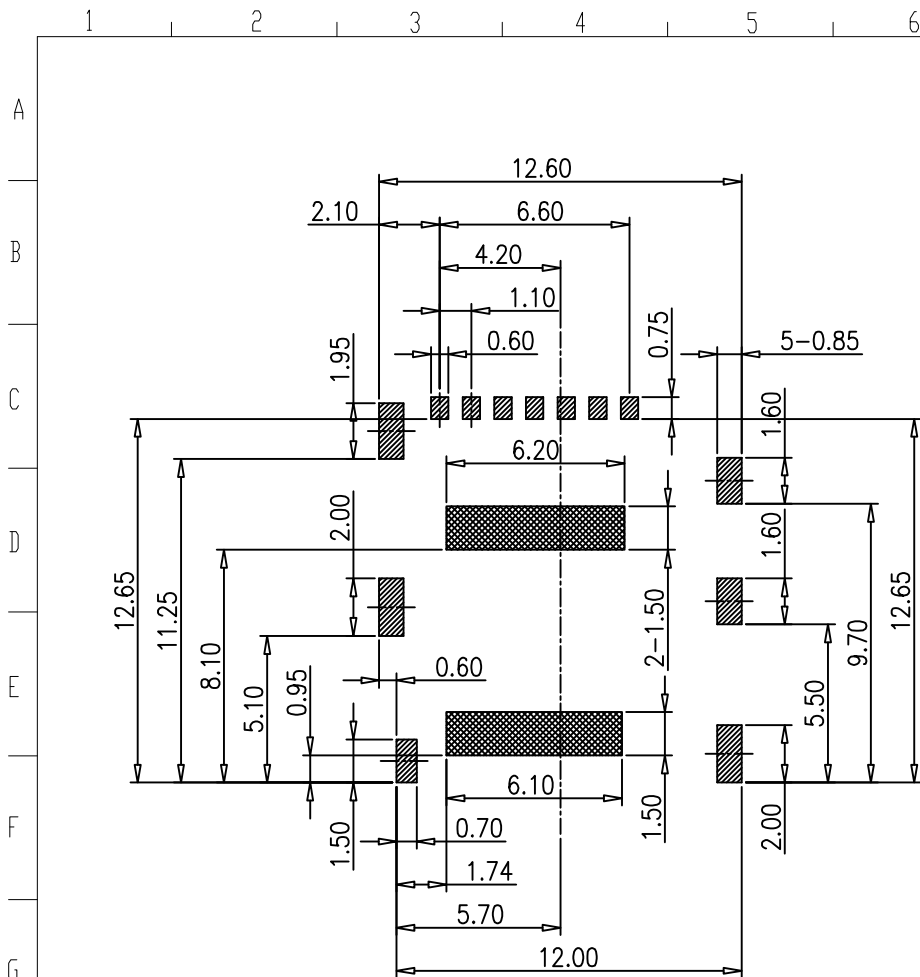
Nano SIM Circuit Description:

PIN No.	FUNCTION
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

7	SPRING	1	THERMOPLASTIC RATING UL94V-0
6	LINK	1	STAINLESS STEEL
5	SLIDE	1	STAINLESS STEEL
4	DETECT PIN	1	COPPER ALLOY
3	CONTACT	1	COPPER ALLOY
2	SHELL	1	STAINLESS STEEL
1	HOUSING	1	LCP UL94V-0
NO.	DESCRIPTION	Q'TY	Material



GENERAL TOLERANCE		KINGCONN 皇海科技股份有限公司	
X± 0.50	X*± 5 °	名 稱(TITLE) NANO SIM CARD PUSH PUSH 7PIN 1.24H 無柱	
.X± 0.30	.X*± 2 °		
.XX± 0.20	.XX*± 1 °		
單 位(UNIT) mm	料 號(PART NO.) 7SIMC-F0-0013	圖 號(DWG NO.) 7SIMC-F0-0013	比例 1:1
審 核(APPROVAL)	檢 查(CHECKED)	製 圖(DRAWN)	圖 數 SHEET 1/2
		PROJ.	更 改 REV B



 SMT SOLDER AREA.
 NO PATTERN AREA

RECONNED PCB LAYOUT
 ALL TOLERANCE $\pm 0.05\text{MM}$

NOTES:

1. FINISH:

1.1 CONTACT:

50u"MIN NICKEL UNDER PLATED,1u"MIN GOLD PLATING ON CONTACT AREA,GOLD FLASH PLATING ON SOLDERING AREA

1.2 SHELL:

30u"NICKEL UNDER PLATED;
GOLD FLASH PLATING ON SOLDERING AREA.

2.ELECTRICAL REQUIREMENTS:

2.1 RATED CURRENT:0.5A

2.2 CONTACT RESISTANCE:100mΩ MAX

2.3 INSULATION RESISTANCE:1000MΩ MIN 200V DC FOR 1 MINUTE

2.4 DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR 1 MINUTE.

3.MECHANICAL REQUIREMENTS:

DURABILITY:3000 CYCLES MIN.

4.ENVIRONMENTAL REQUIREMENTS:

4.1 OPERATING TEMP:-30℃~+85℃

4.2 STORAGE TEMP:-40℃~+85℃

5.RECOMMENDED PROCESS DONDITION:

IR-REFLOW,PEAK TEMPERATURATURE AND TIME:250℃,5-10S

6.METALMASK THICKNESS 0.10MM MIN



GENERAL TOLERANCE		KINGCONN 皇海科技股份有限公司	
X $\pm$ 0.50	X* $\pm$ 5 °	名 稱(TITLE) NANO SIM CARD PUSH PUSH 7PIN 1.24H 無柱	圖 號(DWG NO.) 7SIMC-F0-0013
.X $\pm$ 0.30	.X* $\pm$ 2 °		
.XX $\pm$ 0.20	.XX* $\pm$ 1 °		
單 位(UNIT) mm	料 號(PART NO.) 7SIMC-F0-0013	圖 號(DWG NO.) 7SIMC-F0-0013	圖 號(DWG NO.) 7SIMC-F0-0013
審 核(APPROVAL)	核 對(CHECKED)	製 圖(DRAWING)	圖 號(DWG NO.) 7SIMC-F0-0013
		SCALE 1:1	張 數 2/2
		PROJ.	更 改 REV B